# DTIP 2017

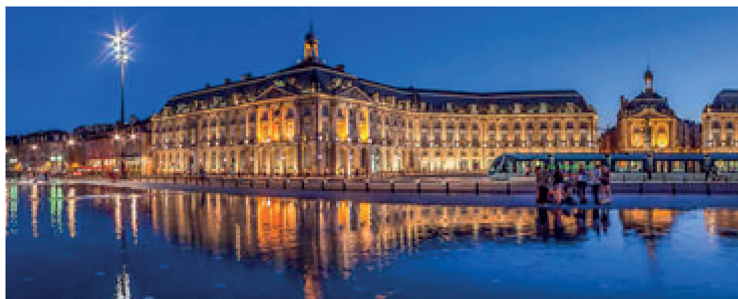
## Design, Test, Integration & Packaging of MEMS/MOEMS

## Final Call for Papers

General Chair: Pascal NOUET, LIRMM, France
Local Chair: Claude PELLET, IMS, France
Publication Chair: Benoit CHARLOT, IES, France

**Bordeaux, FRANCE**

**May, 29th-June, 1st, 2017**



**Submission Deadline:** December, 2nd, 2016
**Notification of Acceptance:** January, 30th, 2017

**http://www.dtip-mems.org/**

DTIP2017 will be the 19th edition of the Symposium on Design, Test, Integration & Packaging of MEMS and MOEMS.
This unique single-meeting event brings together participants interested in MEMS/MOEMS processing and those interested in design tools and methods to facilitate the design of MEMS/MOEMS. All aspects are addressed in two main Conferences, Special Sessions and Invited Talks. Papers presented at the conference will appear in IEEE Xplore and extended version of the presented papers may be submitted for inclusion in a special issue of an indexed journal.
We look forward to welcoming you in Bordeaux.

## Computer-Aided Design, Design and Test

**Chair: Peter Schneider, Fraunhofer IIS/EAS, Dresden, Germany**
**Co-Chair: Francis Pressecq, CNES, France**

This Conference will bring together researchers, engineers and practitioners involved in the development of CAD tools and design methodologies for MEMS and MOEMS.

### Topics of Interest

**CAD**: Integrated CAD/CAE tools, languages and interchange of data, MEMS/MOEMS libraries and IP, Modelling and simulation of fabrication processes, Structured design methodologies, System-level design methodologies

**DESIGN**: Mechanical simulation, Model order reduction, Multi-physics & Multi-domain simulations, Numerical simulation, other design issues, Signal processing & Front-ends, Thermal evaluation

**TEST**: Failure mechanisms, Fault modelling, Fault simulation and test pattern generation, Yield estimation

**DEVICES & COMPONENTS**: RF MEMS, MOEMS, energy harvesting, bio and fluidics, Inertial and Resonant sensors, other sensors & actuators

## Microfabrication, Integration and Packaging

**Chair: Yoshio Mita, Univ of Tokyo, Japan**
**Co-Chair: Stewart Smith, The University of Edinburgh, UK**

This Conference will bring together researchers, engineers and practitioners involved in the development of integration technologies and packaging for MEMS and MOEMS.

### Topics of Interest

**MICROFABRICATION**: assembly technologies, microlithography issues for MEMS/MOEMS, micromachining, micro-molding, nano-imprint, embossing, others

**INTEGRATION**: flexible technologies and printed electronics, co-integration between MEMS and electronics, 3Dtechnologies

**PACKAGING**: MOEMS, RF and microwave, vacuum and other harsh environments, others

**MATERIALS**: piezoelectric, PDMS, others

**CHARACTERIZATION**: dimensional measurements, non-destructive evaluation, PCM & Test structures, physical measurements, reliability and failure analysis

**DEVICES & COMPONENTS**: RF MEMS, MOEMS, energy harvesting, bio and fluidics, Inertial and Resonant sensors, other sensors & actuators